

## TRANSMITTAL

Electronic Version v1.1

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|  |   |                |               |             |                |  |               |       |
|--|---|----------------|---------------|-------------|----------------|--|---------------|-------|
| <b>Title of<br/>Invention</b>  | <b>[QUAD FLAT NO-LEAD PACKAGE STRUCTURE AND<br/>MANUFACTURING METHOD THEREOF]</b> |                |               |             |                |  |               |       |
| Application Number :   |   |                |               |             |                |  |               |       |
| Date :   |   |                |               |             |                |  |               |       |
| First Named Applicant:   | Mr. Jui-Hsiang Pan  |                |               |             |                |  |               |       |
| Confirmation Number:   |   |                |               |             |                |  |               |       |
| Attorney Docket Number:  | 11537-US-PA   |                |               |             |                |  |               |       |
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| <table border="1"><tr><td>Submitted By:</td><td>Elec. Sign.</td><td>Sign. Capacity</td></tr><tr><td>Dr. Belinda Lee<br/>Registered Number: 46,863</td><td>/Belinda Lee/</td><td>Agent</td></tr></table>  |   |                | Submitted By: | Elec. Sign. | Sign. Capacity | Dr. Belinda Lee<br>Registered Number: 46,863 | /Belinda Lee/ | Agent |
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| Dr. Belinda Lee<br>Registered Number: 46,863   | /Belinda Lee/   | Agent          |               |             |                |  |               |       |

| Documents being submitted:  | Files  |
|---|--|
| us-assignment   | 11537-usassn.xml<br>us-assignment.xsl<br>us-assignment.dtd<br>11537assignment1.tif<br>11537assignment2.tif   |
| us-request  | 11537-usrequ.xml<br>us-request.dtd<br>us-request.xsl   |
| us-fee-sheet  | 11537-usfees.xml<br>us-fee-sheet.xsl<br>us-fee-sheet.dtd   |
| us-declaration  | 11537declaration1.tif  |
| us-declaration  | 11537declaration2.tif  |
| application-body  | 11537-trans.xml<br>us-application-body.xsl<br>application-body.dtd<br>wipo.ent<br>mathml2.dtd<br>mathml2-qname-1.mod<br>isoamsa.ent<br>isoamsb.ent<br>isoamsc.ent<br>isoamsn.ent<br>isoamso.ent<br>isoamsr.ent<br>isogr3.ent<br>isomfrk.ent<br>isomopf.ent<br>isomscr.ent<br>isotech.ent<br>isobox.ent<br>isocyr1.ent<br>isocyr2.ent<br>isodia.ent<br>isolat1.ent<br>isolat2.ent<br>isonum.ent<br>isopub.ent<br>mmlextra.ent<br>mmlalias.ent<br>soextblx.dtd<br>11537us0001.tif<br>11537us0002.tif<br>11537us0003.tif<br>11537us0004.tif<br>11537us0005.tif<br>11537us0006.tif |
| <b>Comments</b>   |  |
| Please be kindly advised that the indicated fees of this EFS application is intended to be paid by credit card. |  |

However, in the event that the payment through credit card is unsuccessful, the Commissioner is authorized to charge the required fees in connection with this application to: Deposit Account No. 50-2620 (Order No. 11537-US-PA ), Deposit Account Name: Jianq Chyun Intellectual Property Office, Authorized User Name: Belinda Lee, E-mail: belinda@jcipgroup.com.tw; usa@jcipgroup.com.tw